

TSMC97-306

Reissue Application no. 10/062,314

Reissue Application of Patent No. 6,019,906

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August 30, 2003

Commissioner of Patents and Trademarks
Washington, D.C. 20231

FROM: George O. Saile, Reg. No. 19,572
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SUBJECT: **Reissue Application of:**
Patent #: 6,019,906
Issue Date: Feb. 1, 2000
Inventor: Syun-Ming Jang, Ming-Hsin Huang
Title: Hard Masking Method for Forming Patterned Oxygen
Containing Plasma Etchable Layer

Reissue Serial Number: **10/062,314**
Reissue File Date: **Feb. 1, 2002**

RESPONSE TO OFFICE ACTION

This is in response to the office action dated July 30, 2003. Please amend the
above-identified Reissue application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States
Postal Service as first class mail in an envelope addressed to: Commissioner of
Patents and Trademarks, Washington, D.C. 20231 on *September 2, 2003*

Signature 
Stephen B. Ackerman, Reg. No. 37,761

Date: 9/2/03